

Appln. No. 10/532,949
Response dated June 19, 2008 to
Reply to Office Action of March 28, 2008

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REMARKS

Reconsideration of the present application, as amended, is respectfully requested.

The March 28, 2008 Office Action and the Examiner's comments have been carefully considered. In response, the Abstract of the Disclosure and claims are amended, and remarks are set forth below in a sincere effort to place the present application in form for allowance. The amendments are supported by the application as originally filed. Therefore, no new matter is added.

SPECIFICATION

In the Office Action, the Examiner objects to the Abstract of the Disclosure, contending that it exceeds 150 words in length. In response, the Abstract of the Disclosure is amended to more clearly comply with the requirements of MPEP §608.01(b). A clean copy of the Abstract is enclosed herewith.

In view of the amendment of the Abstract of the Disclosure, reconsideration and withdrawal of the objection to the Abstract of the Disclosure are respectfully requested.

CLAIM OBJECTIONS

In the Office Action, claims 1, 2, 6 and 7 are objected to because of certain informalities. In response, claims 1, 2, 6

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and 7 are amended to correct the informalities cited by the Examiner. In view of the amendment of claims 1, 2, 6 and 7, reconsideration and withdrawal of the objection to the claims are respectfully requested.

REJECTION UNDER THE SECOND PARAGRAPH OF 35 USC 112

In the Office Action, claims 6 and 7 are rejected under the second paragraph of 35 USC 112 as being indefinite for failing to particularly point and distinctly claim the subject matter which Applicants regard as the invention.

In response, claims 6 and 7 are amended to be in more traditional format for method claims.

In view of the amendment of claims 6 and 7, reconsideration and withdrawal of the rejection of claims 6 and 7 under the second paragraph of 35 USC 103 are respectfully requested.

PRIOR ART REJECTIONS

In the Office Action claims 1-3, 5-7 and 16 are rejected under 35 USC 102(b) as being anticipated by USP 6,063,647 (Chen et al.), or in the alternative, under 35 USC 103(a) as obvious over Chen et al. in view of Applicants' admitted prior art (AAPA). Claims 4 and 17-19 are rejected under 35 USC 103(a) as being unpatentable over Chen et al. in view of USP 5,352,314 (Coplan).

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Chen et al. disclose a method of making a multilayer circuit by combining circuit elements 20 and 21. The structural element 36 of Chen et al., which the Examiner contends corresponds to the weak-adherence adhesive pattern of the present claimed invention, is actually an insulating layer provided between two circuit elements (i.e., substrates on which conductive parts are provided), and is originally provided on the entire surface of the substrate 22 of the structural element 20, as shown in Fig. 1a of Chen et al. As shown in Fig. 1b of Chen et al., at least a portion of the insulating layer 36 is removed, so as to expose a portion of the bump 30, which is provided between the two circuit elements when they are combined.

The structural element 36 of Chen et al. is an inter-layer insulating film, which is provided between the two circuit elements 20, 21 (see Chen et al. at column 5, lines 53-58). Chen et al. do not, however, disclose, teach or suggest a holding and conveyance jig for holding a printed circuit board or a conductive material laminated plate for manufacturing a printed circuit board as defined by the present claims. The structural element 22 of Chen et al., which the Examiner contends corresponds to the holding and conveyance jig of the present claimed invention, is a substrate of circuit element 20 (see Chen et al. at column 4, lines 44-52). Chen et al. and the present invention belong to different technical fields, and Chen et al.

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do not disclose, teach or suggest the weak adherence adhesive pattern.

In Applicants' Admitted Prior Art (AAPA), the paragraph indicated by the Examiner teaches a weak-adherence adhesive layer which is formed on the entire surface of the relevant jig.

The inter-layer insulating film of Chen et al. is originally provided on the entire surface of the substrate 22 of the structural element 20 (see Fig. 1a). As shown in Fig. 1b, at least a part of the insulating layer 36 is removed, so as to expose a part of the bump 30, which is provided between the two circuit elements when they are combined.

As described above, Chen et al. do not disclose a holding and conveyance jig for holding a printed circuit board or a conductive material laminated plate for manufacturing a printed circuit board. The inter-layer insulating film 36, a part of which is removed, is an element interposed by the two circuit elements. Therefore, the insulating film 36 is not formed on a surface of a plate of a holding and conveyance jig. In other words, never a part of the holding and conveyance jig.

Accordingly, even if Chen et al. is combined with AAPA, the references do not disclose, teach or suggest:

(i) a weak-adherence adhesive pattern formed on a surface of a plate of a jig for holding and conveyance, and at a position corresponding to a non-conductive portion of the relevant printed

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circuit board, and/or

(ii) a weak-adherence adhesive layer formed on a surface of a plate of a jig for holding and conveyance, and a weak-adherence pattern subjected to surface roughening formed on a surface of the weak-adherence adhesive layer at a position corresponding to a conductive portion of the relevant printed circuit board.

With regard to (ii) above (corresponding to claim 2), a portion of the entire weak-adherence adhesive layer is subjected to surface roughening. This is also completely different from a partial removal of an inter-layer insulating film so as to establish a connection with a conductive body (i.e., bump 30) provided between two circuit elements.

Independent claims 1 and 2 are patentable over the references of record for reasons, inter alia, set forth above. Claims 3-5, which are either directly or indirectly dependent on claims 1 or 2, are patentable over the references of record in view of their dependence on claims 1 or 2 and because the references do not disclose, teach or suggest each of the limitations set forth in claims 3-5.

Claims 6 and 7 are method claims which correspond to claims 1 and 2. Claims 6 and 7 are patentable over the cited references for reasons, inter alia, set forth above in connection with claims 1 and 2.

Claims 16-19 are dependent on claims 1 or 2, and are

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patentable over the cited references in view of their dependence on claims 1 or 2, and because the references do not disclose, teach or suggest each of the limitations set forth in claims 16-19.

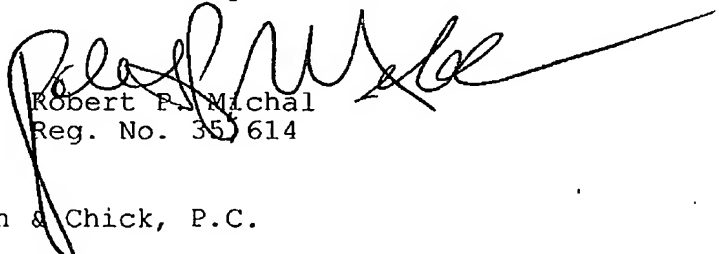
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Entry of this Amendment, allowance of the claims and the passing of this application to issue are respectfully solicited.

If the Examiner disagrees with any of the foregoing, the Examiner is respectfully requested to point out where there is support for a contrary view.

If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned at the telephone number given below for prompt action.

Respectfully submitted,



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Encl.: Substitute Abstract of the Disclosure